

58	3056	257/774	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
59	3556	257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
60	957	257/782	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
61	1482	257/783	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
62	2329	257/784	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
63	2372	257/786	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
64	16528	257/668 257/676 257/688 257/694 257/698 257/737 257/738 257/739 257/774 257/778 257/782 257/783 257/784 257/786	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
65	488	((hole recess trench gap cavity opening) and (substrate wafer) and (electrode bump) and (interconnect\$3 adj2 (pattern film layer))) and (257/668 257/676 257/688 257/694 257/698 257/737 257/738 257/739 257/774 257/778 257/782 257/783 257/784 257/786)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:44